



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Applicant: Leonard Forbes et al.

Title: STRAINED SEMICONDUCTOR BY FULL WAFER BONDING

Docket No.: 1303.109US1

Serial No.: 10/623,788

Filed: July 21, 2003

Due Date: N/A

Examiner: Unknown

Group Art Unit: 2811

MS Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ A Communication Concerning Related Applications (2 pgs.).
- ☒ A Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (2 pgs.), and copies of 11 cited documents.

If not provided for in a separate paper filed herewith, Please consider this a **PETITION FOR EXTENSION OF TIME** for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

By: *Marvin L. Beekman*

Atty: Marvin L. Beekman

Reg. No. 38,377

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 4 day of May, 2005.

Name

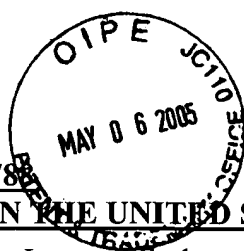
KACIA LEE

Signature

Kacia Lee

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)



S/N 10/623,788

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Leonard Forbes et al. Examiner: Unknown
Serial No.: 10/623,788 Group Art Unit: 2811
Filed: July 21, 2003 Docket: 1303.109US1
Title: STRAINED SEMICONDUCTOR BY FULL WAFER BONDING

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
10/443355	May 21, 2003	1303.098US1	SILICON OXYCARBIDE SUBSTRATES FOR BONDED SILICON ON INSULATOR
10/931554	August 31, 2004	1303.093US2	LOCALIZED STRAINED SEMICONDUCTOR ON INSULATOR
10/931749	August 31, 2004	1303.095US2	STRAINED SEMICONDUCTOR BY WAFER BONDING WITH MISORIENTATION
10/931344	August 31, 2004	1303.108US2	GETTERING USING VOIDS FORMED BY SURFACE TRANSFORMATION
10/931553	August 31, 2004	1303.099US2	ULTRA-THIN SEMICONDUCTORS BONDED ON GLASS SUBSTRATES
10/931580	August 31, 2004	1303.100US2	MICROMECHANICAL STRAINED SEMICONDUCTOR BY WAFER BONDING
10/979994	November 3, 2004	1303.102US2	STRAINED Si/SiGe/SOI ISLANDS AND PROCESSES OF MAKING SAME
11/005712	December 7, 2004	1303.034US2	THREE-DIMENSIONAL PHOTONIC CRYSTAL WAVEGUIDE STRUCTURE AND METHOD

COMMUNICATION CONCERNING RELATED APPLICATIONS

Serial Number: 10/623,788

Filing Date: July 21, 2003

Title: STRAINED SEMICONDUCTOR BY FULL WAFER BONDING

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Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicant requests that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,

LEONARD FORBES ET AL.

By Applicants' Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
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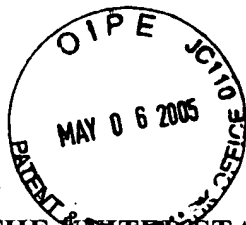
Date 5-4-05 By 
Marvin L. Beekman
Reg. No. 38,377

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KACIA LEE
Name

Kacia Lee
Signature

S/N 10/623,788



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Leonard Forbes et al.	Examiner:	Unknown
Serial No.:	10/623,788	Group Art Unit:	2811
Filed:	July 21, 2003	Docket:	1303.109US1
Title:	STRAINED SEMICONDUCTOR BY FULL WAFER BONDING		

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Supplemental Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Supplemental Information Disclosure Statement considered.

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Serial No :10/623,788

Filing Date: July 21, 2003

Title: STRAINED SEMICONDUCTOR BY FULL WAFER BONDING

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The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).


Respectfully submitted,

LEONARD FORBES ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 373-6960

Date 5-4-05

By 
Marvin L. Beekman
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Name KACIA LEE

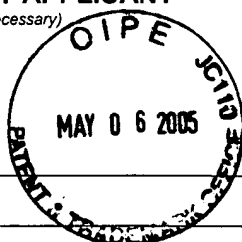

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Substitute for form 1449A/PTO

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use as many sheets as necessary)



Complete if Known

Application Number	10/623,788
Filing Date	July 21, 2003
First Named Inventor	Forbes, Leonard
Group Art Unit	2811
Examiner Name	Unknown

Sheet 1 of 2

Attorney Docket No: 1303.109US1

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date If Appropriate
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EXAMINER

DATE CONSIDERED

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	Application Number	10/623,788
	Filing Date	July 21, 2003
	First Named Inventor	Forbes, Leonard
	Group Art Unit	2811
	Examiner Name	Unknown
Sheet 2 of 2	Attorney Docket No: 1303.109US1	

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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EXAMINER

DATE CONSIDERED